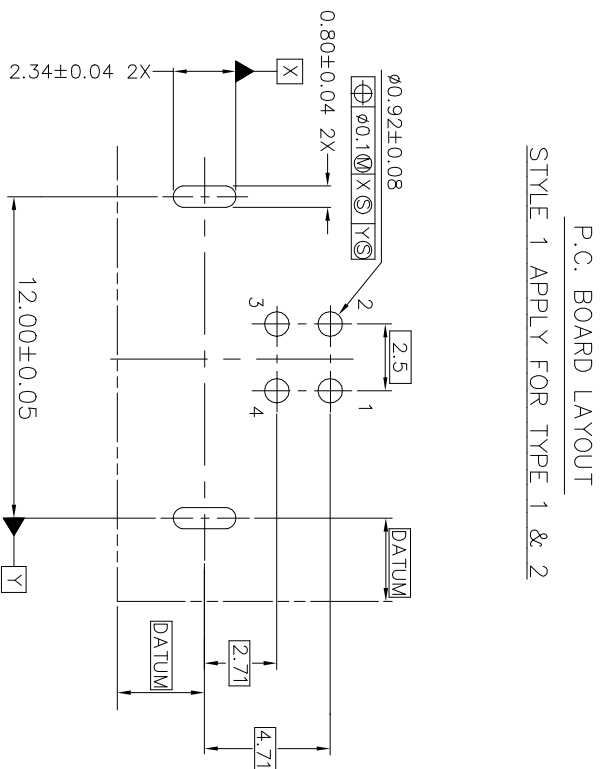
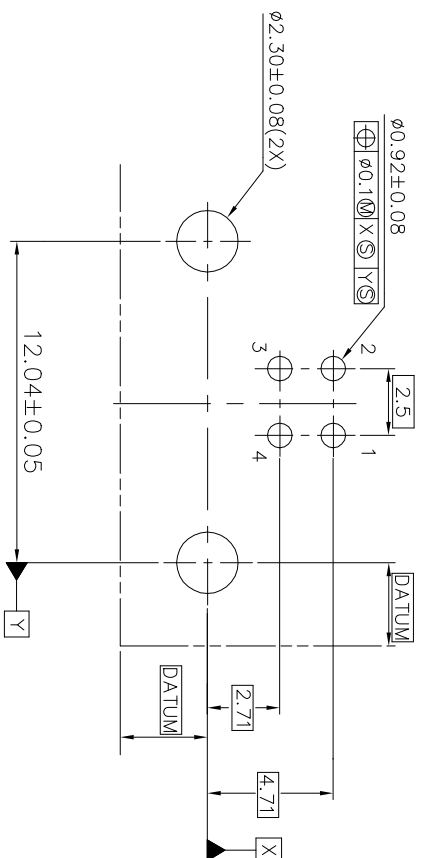




- NOTES:
1. MATERIAL:
SHIELD & CONTACTS: COPPER ALLOY
HOUSING: UL 94V-0 ,HIGHT TEMPERATURE THERMOPLASTIC.
COLOR: SEE PRODUCT NUMBER CODE.
 2. PLATING: SEE PRODUCT NUMBER CODE.
SHIELD: BRIGHT TIN, NICKEL UNDERPLATE(USED FOR WAVE SOLDER PROCESS),
PLATING NICKEL ONLY(USED FOR PIP PROCESS).
 3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
 4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)
 5. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
 6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
 7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C
PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR
PHASE REFLOW OVEN.
 8. THE PART CAN BE USED FOR PIP PROCESS.

mat'l. code		surface ✓ tolerance		projection 110° 		product family	
		ISO 1302 ✓ ISO 406 ISO				HPL 511 USB2.0	
litr ecn no dr		date		tolerances unless otherwise specified		title	
Y				angles linear 0.0±0.30 0.000±0.10		USB RECEPTACLE B TYPE	
				0°±2°			
				dr Laurence,Zong 02/26/19		dwg no sheet2 of 2 size	
				enjl Laurence,Zang 02/26/19		61729 A3	
				chr Tim. Yao 02/26/19			
				qppd Tim. Yao 02/26/19			
sheet revision						type Product Customer Drawing	
index sheet							